

LAST - (Untitled:1)

Drafts Pending Active

L1: (1390) (semiconductor near (chip die IC)) with polymer
 L2: (4) (semiconductor near (chip die IC)) with polymer with (1)
 L4: (4) 2 and (@ad<"20040924" @rlad<"20040924")
 L5: (59) (semiconductor near (chip die IC)) and (polymer with (1)
 L6: (59) 5 and (@ad<"20040924" @rlad<"20040924")
 L10: (4) polymer with (encapsulants3) near3 (active near surface)
 L11: (4) 10 and (@ad<"20040924" @rlad<"20040924")
 L12: (17) polymer with (encapsulants3) near3 (bond near wires3)
 L13: (17) 12 and (@ad<"20040924" @rlad<"20040924")
 L14: (0) 257/666.ccls. and (polymer with (encapsulants3) near3)

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DB: US-PGPUB; USPAT; USOCR; EPO; JPO; DERVENT; IBM_TOB

Default operator: OR Purge Highlight all hit terms initially

12 and (@ad<"20040924" @rlad<"20040924")

BRSform ISRform Image Tec HTML

U	1	Document ID	Issue Date	Pages	Title	Current OR	Current Xref	Retrieval C	Inventor	S	C	P	3
1	P	US 6392291 B1	20020521	18	Semiconductor component having selected terminal	257/678	257/698; 257/734;		Corisis; David J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
2	P	US 6391681 B1	20020521	17	Semiconductor component having selected terminal	438/106	257/E21.508; 257/E23.07		Corisis; David J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
3	P	US 6537850 B1	20030325	17	Method for fabricating semiconductor components	438/106	257/E21.508; 257/E23.07;		Corisis; David J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
4	P	US 20030207501 A1	20031106	16	Semiconductor component with adjustment circuitry and	438/128	257/E23.171; 438/131;		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
5	P	US 20040009631 A1	20040115	16	Semiconductor package with circuit side polymer layer	438/127	257/E21.508; 257/E23.039;		Connell, Mike et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
6	P	US 6753482 B1	20040622	14	Semiconductor component with adjustment circuitry	174/261	174/255; 257/E23.171		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
7	P	US 20040135253 A1	20040715	16	Semiconductor component with electrical characteristic	257/738	257/E23.171		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
8	P	US 20040171191 A1	20040902	16	Stacked semiconductor package with circuit side	438/112	257/782; 257/784;		Connell, Mike et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
9	P	US 6791168 B1	20040914	14	Semiconductor package with circuit side polymer layer	257/668	257/737; 257/784;		Connell, Mike et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
10	P	US 20040201111 A1	20041014	11	Interposer substrates with multisegment interconnect	257/782	257/780; 257/783;		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
11	P	US 20040201075 A1	20041014	9	Semiconductor die configured for use with interposer	257/459	257/E23.004		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
12	P	US 20040200063 A1	20041014	10	Interposer substrates with multi-segment interconnect	25/830	257/E23.004; 25/846;		Thurgood, Blaine J.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>
13	P	US 6753482 B1	20040622	14	Semiconductor component	257/738	257/E23.004; 257/780;		Schoenfeld, Aaron M. et al.	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>

Ready

THN